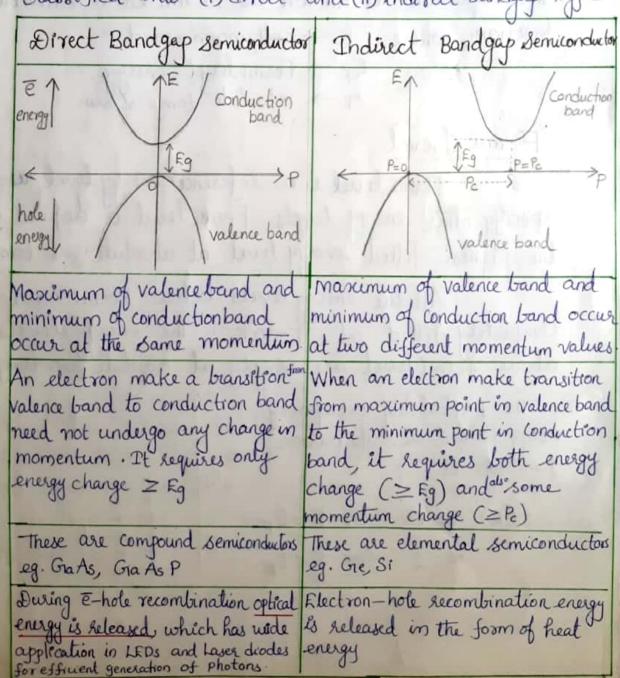
JESSY

PHYSICS SEMICONDUCTOR

MODULE 3

Direct and Indirect Bandgap Semiconductors

Using energy (E) - momentum (P) relationship the energy of a free electron is $E = \frac{P^2}{2m}$. Energy-momentum relation is parabolic in nature (EXP) The energy of free electrons in the conduction band is representing by an upper parabola and holes in valence band by lower parabola. The gap between two parabolas at P=0 is the bandgap Eg. Acco to energy momentum relationship semiconductors are classified into (i) direct and (ii) indirect bandgap type

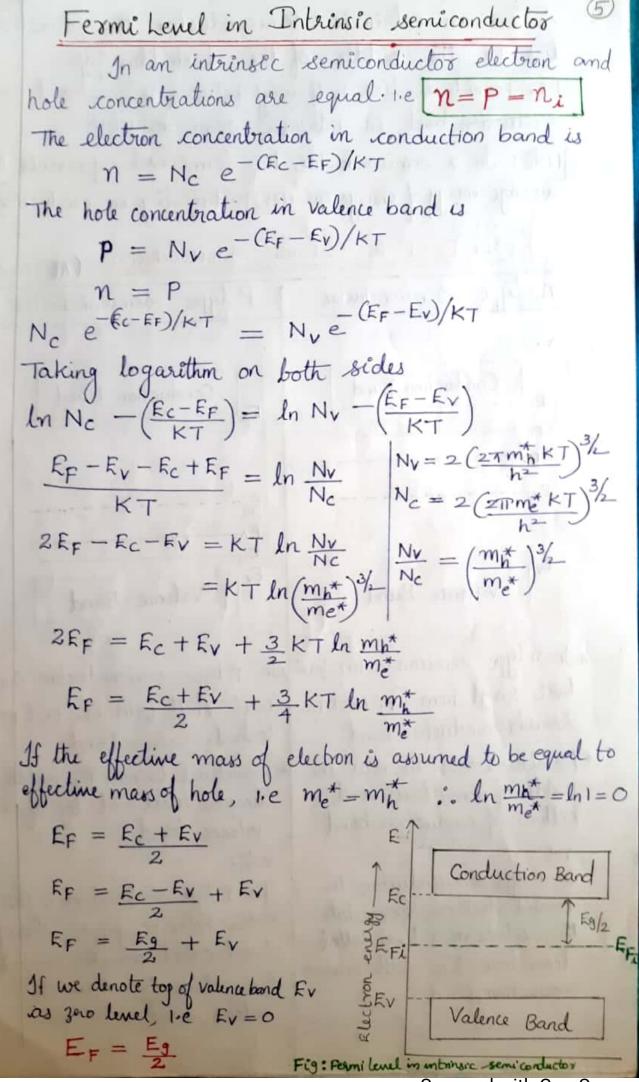


= 1 for E<EF

electrons occurs. That is, the electrons having energy a lettle below EF, jump into levels above EF. Therefore probability of finding electrons in the levels below EF will declease and that of levels above EF will increase.

At T>OK, for E= EF f(E) = 1+e = 1+e = 1+1 = = = 0.5 = 50%

f(E)1 This implies that the probability of occupancy of femilevel at any temperature above ok is 0.5 or 50%. Therefore at temperatures above OK, is Fermi energy is defined as the average energy possessed by electrons participating in conduction process in a conductor-Carrier concentration in Semiconductor Career concentration is the number of electrons in the conduction band per unit volume (n) and the number of holes is in the valence, band per unit volume (P) of the material. Carrer concentration is also known as density of charge coveriers Electron concentration in conduction band (n) $n = N_c e^{-(E_c - E_F)/KT}$ where No is a constant known as effective density of states in conduction band No = 2 [217 me K T] 3/2 where me - effective mass of e Hole Concentration in valence band (P) P = Ny e - (EF-EV)/KT where NV is called effective density of states in valence band $N_V = 2 \left[\frac{2\pi m_h^* kT}{h^2} \right]^{3/2}$ where mn + -> effective man of holes



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i. In an intrinsic semiconductor the fermilevel lies in the middle of the forbidden gap. 1. e. Fermilevel lies half-way between valence band and conduction band in intrinsic semiconductor. Note: In a semiconductor, the fermilevel represents the average energy of charge carriers participating in conduction Fermi Level in Extrinsic semiconductor (At T=OK)	
n type elemiconductor	Ptype Semiconductor
Conduction Band Ern ED Ex Valence Band * In n type semiconductor fermi	Conduction Band Ex Ex Ex Valence Band In physics semiconductor fermi
level shift from Exito Exn	level shift from EFi to EFP
towards conduction band	towards valence bands
bottom of conduction band note: In mype semiconductor, the	receptor level and top of the valence band. note: Pro P type semiconductor, the
donated electrons accommodate them selves in a level called donor level ED, little below-conduction band	extra holes occupy an energy level level called acceptor energy level EA, which is above the valence band.

I. Effect of temperature on Fermi Level
(1) In n type semiconductor

In n type semiconductor at low temperatures, some donor atoms are ionized and provide electrons to the conduction band; while other remains neutral. As electrons in the conduction band are only due to transition from donor levels, the Fermilevel must be between the donor energy level and bottom of conduction band.

When T=OK, EFn lies midway between the donor levels and bottom of the conduction band. As the temperature increases the donor levels gradually get depleted and the Fermilevel moves downward. At the temperature of complete depletion of donor levels, Ta, the fermilevel coincide with donor level ED

 $E_{Fn} = \frac{E_C + E_D}{2}$ at T = 0kconduction Frn = FD at T=Td Ec (depletion temp) EFT Further increase in temperature above Td, lead to downward shift of fermi level in a linear fashion At a temp Ti, the intrinsic Ev Valence Band behaviour contributes to electron concentration. At higher temperation 100 200 300 400 T(K) the n type semiconductor loves its extrinsic character and behaves as an intrinsic semiconductor. In the intrinsic region femilevel approaches the intrinsic value EFn = EFe = Eq at T≥ Te where Te is intrinsic

(8) (2) In P type semiconductor

In p type semiconductor, at low temperature holes in the valence band are only due to transition of electrons from valence band to the acceptor level. As valence band is the source of electrons and the acceptor levels are the recipients for them, the fermi level must lie between the top of valence band and acceptor energy level

When T=OK, fermi level Explies midway between acceptor level and top of valence band.

As the temperature increases, the acceptor levels gradually get filled and the fermi level moves upward. At the temperature of saturation of acceptor levels, Ts, the fermi level coincide with the acceptor level Ex

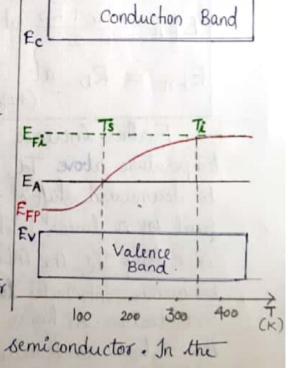
 $E_{FP} = \frac{E_V + E_A}{2}$ at T = 0k $E_{FP} = E_A$ at $T = T_S$ (saturation temp.)

Further increase in temperature above Ts, result in reproard shift of fermi level

At a temperature Ti, intrinsic behaviour sets in. At higher temperature, the p type semiconductor loses its extrinsic character

and behaves as an intrinsic semiconductor. In the intrinsic segion fermi level approaches the intrinsic value.

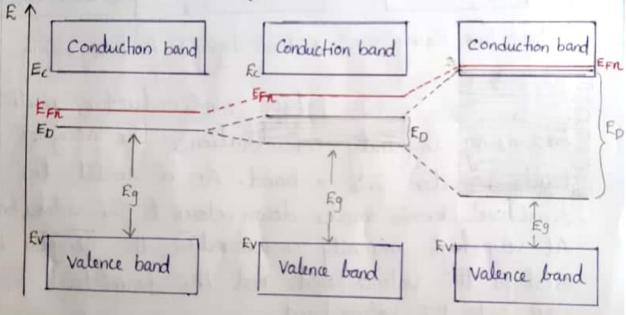
$$E_{FP} = E_i = \frac{E_g}{2}$$
 at $T = T_i$



II. Effect of impurity concentration on Fermi Level

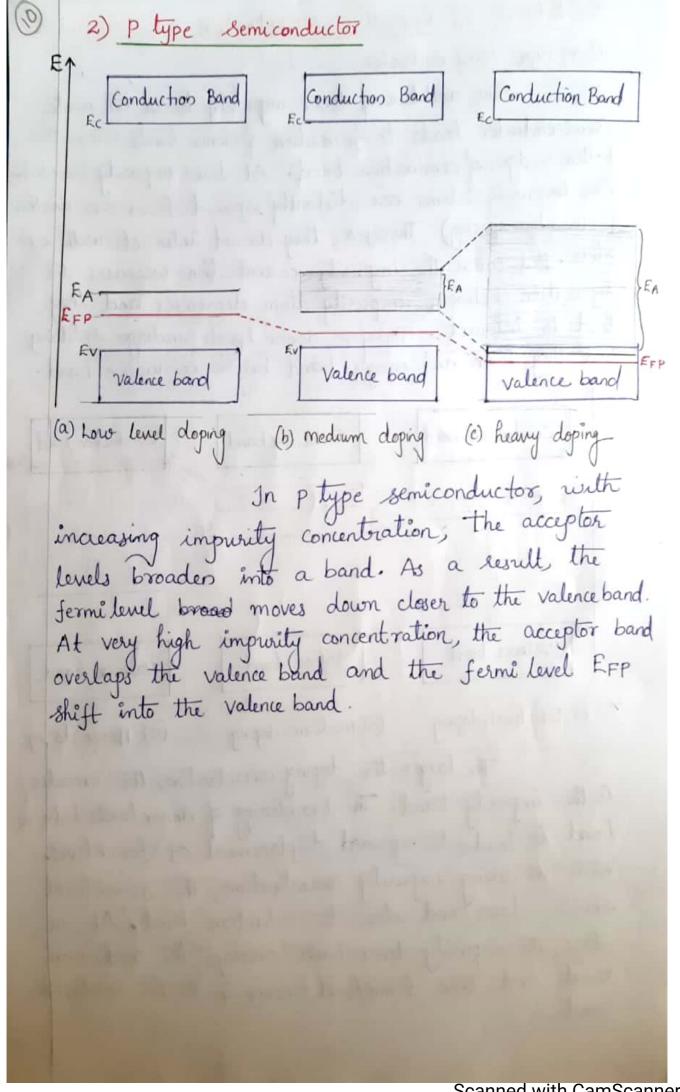
1) n type semiconductor

The addition of donor impririty to an intrinsic semiconductor leads to formation of donor levels below the bottom edge of conduction band. At low impririty concentration, the imprivity atoms are distantly spaced from one another (\$100 atom spacing). Therefore, they do not interact with each other. But when the impririty concentration increases the separation between impurity atom decreases and they tend to interact. Therefore donor levels undergo splitting and they form an energy band below conduction band.



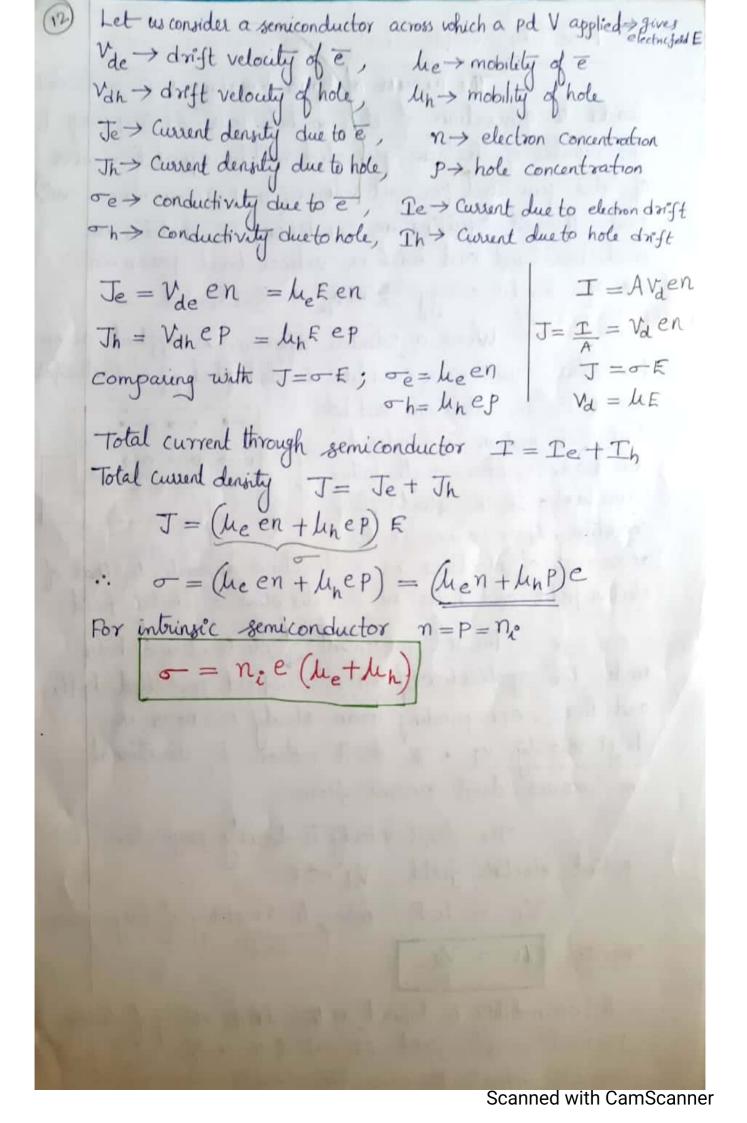
(a) Low level doping (b) medium doping (c) Heavy doping

The larger the doping concentration, the broader is the impurity band. The broadening of donor levels into a band is leads to represent desplacement of fermilevel. With increasing impririty concentration, the fermilevel shifts closer and closer to conduction band. At one stage, the impurity donor band overlaps on the conduction band and then fermi level moves in to the conduction band.



Mobility, Conductivity and Current Density The process of bond breaking in a semiconductor leads to generation of electron-hole pair. At any temp. T the number of electrons generated will be equal to number of holes generated per unit volume (n=P=ni > intrinsic conc) under thumal equilibrium condition, the electrons in conduction band and holes in valence band possess an average kinetic energy = mvth = 3KT O DRIFT CURRENT When a polential difference is applied across the solid, equilibrium condition is disturbed. The electricifeld accelerates the electrons and holes. But their motion is hindered due to interactions with lattice Vibrations. In the sleady state condition, there arises a net movement of electrons in a direction opposite to that of electric field and holes in the direction of electric-field. The net movement of electrons and holes under the application of an electric field is called drift, and their corresponding mean velocity is known as drift velocity va. The drift motion is directional and causes drift current flow The drift velocity is directly proportional to applied electric field VICE Vd = UE where li -> mobility of charge carrier Mobility: M = Va : Electron mobility is defined as the drift velocity of electrons

Per unit electric field. ET unit of u > m2/Vs) semicordula > 10 m2/Vs Mobility indicates the ease with which is more in a solid Scanned with CamScanner



(13

In semiconductors, current can also flow without applying electric field. If there are more charge carriers on its one side, other than on the other side, there is a concentration gradient. This concentration gradient causes a directional movement of charge carriers, which continues until all the carriers are evenly distributed throughout the material. Any movement of charge carriers constitute an electric current and this type of movement produces a current known as diffusion current.

The difference in the concentration of charge carriers initiates the carriers to diffuse from the region of higher concentration to the region of low conc. in order to restore equilibrium condition. As the carriers are charged particles the migration produces a current flow, which is the diffusion current.

Diffusion Current strength \(\infty \text{Concentration gradient}\)
(rate of change of carrier concⁿ per unit length)

The current component due to electron of hole diffusion are

Je (diff) = e De dr when De → Diffusion coefficient due to E Jh (diff) = -e Dh dP Dh Diffusion coefficient due to hole

Drift and diffusion current coexist in semiconductors.

Total current density = drift current density + Diffusion current density for $\overline{e}s \Rightarrow Je = Je (drift) + Je (drift)$

Je = e[nhef + Dedn]

forhole > Jh = e[PhhE - Dh dp]

fore >

14)

HALL EFFECT (by E.H. Hall in 1879)

"If a current carrying conductor or semiconductor is placed in a transverse magnetic field, a potential difference V_H is produced in a direction normal to both magnetic field and current direction. This is known as Hall effect."

Experimental arrangement

F' MB

Experimental arrangement

F' MB

Experimental arrangement

THE TOTAL ARRANGEMENT

Ptype semiconductor

Area = Wt

Mayor charge carrier

> holes

Consider a thin rectangular ptype

semiconductor of thickness 't' and width'w', which is

mounted on an insulating strip. A voltmeter and a

constant current source is connected across it. This

arrangement is placed between two poles of an

electromagnet such that the magnetic-field act is perpendicula

to the lateral faces of semiconductor.

Hall voltage

Before the application of

magnetic field B, holes moves parallel

to face F and F'. After applying magnetic field,

the holes experience sideways deflection due to

magnetic Lorentz force FL. (8

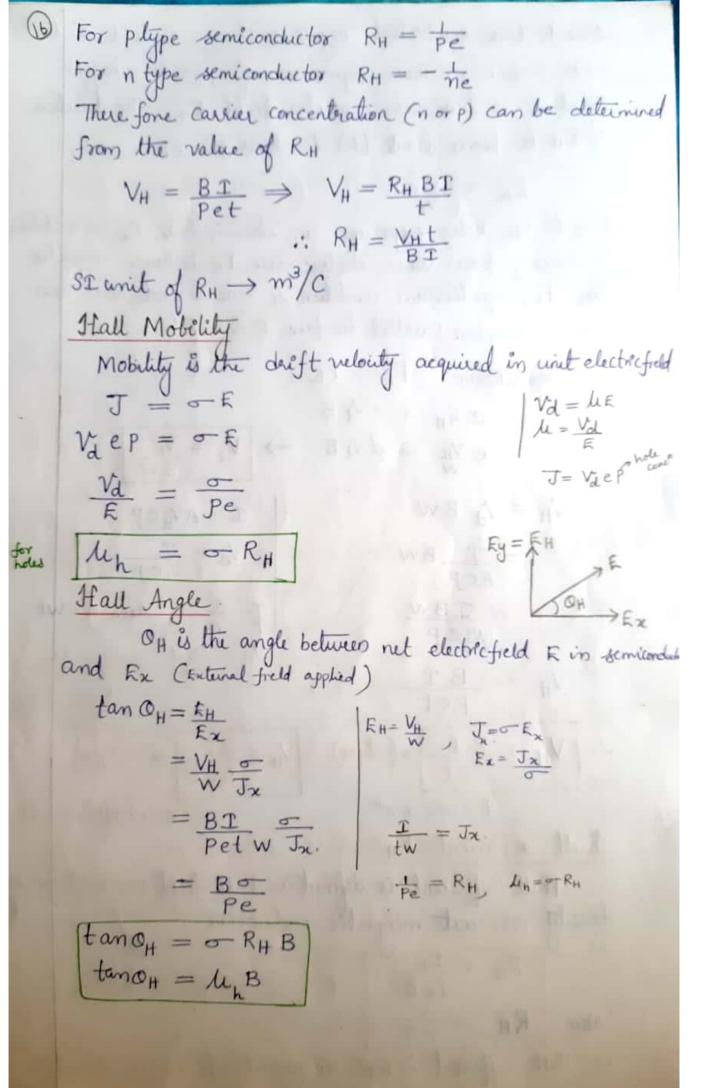
Magnetic Lorentz force FL = e Vd B

Holes are deflected towards the front face F and pile up there

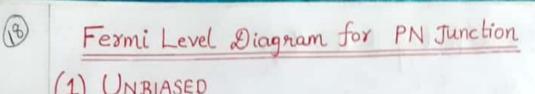
Due to this equivalent negative charge is left on the (5) rear face F'. These separation of opposite charges Produce a transverse electric field, EH. The direction of EH is from front (F) to rear face (F') EH = VH Due to EH, holes experience an electric force FE in addition to Lorentz force When electric force FE balances magnetic force FL, equilibrium condition is reaches and holes flow along x direction parallel to face F and F' At equilibrium FE = FL e EH = e Va B e/VH = & VdB = Vd = VH BW VH = Vd BW I = AVLEP VI = I = I BW J= I , Area A= Wt VH = JxBW ; = RH = P = VH RH = P = EH TxBW VH = BI ·· VH = BI Pet > (Ptype) VH = BI net > (n type) P-> hole conco n -> electron conc? Hall Coefficient RH Hall coefficient is defined as Hall field per unit current density per unit magnetic induction RH = EH Also RH = pe

1.e; Hall coefficient is the reciprocal of charge derinty

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	Factors affecting Hall Voltage (17)	
	Factors affecting Hall Voltage	
	$V_H = \frac{BT}{Pet}$	
*	Hall voltage is directly propostional to mag field strength B and current I passing through the material	
	current I passing through the material	
	Hall voltage is inversely proportional to the charge carrier concentration and thickness of material.	
	. Hall voltage will be larger, the larger the magnetic field	
	or current. Further Hall voltage is larger, the smaller the carrier concentration and thinner the material.	
((note: For semiconductors the number of charge carriers per unit volume is about 1023/m3, while that of metal is about 1028/m3. Therefore, the Hall voltage is about 105	
	greater in semiconductor than in metals)	
	Applications of Hall Effect (Importance of Hall effect)	
	Hall effect helps to determine	
	Hall effect helps to determine Of the type of semiconductor (RH = -ve for ntype) RH = +ve for p type)	
(2) the charge carrier concentration $(n= \frac{1}{R_He} , P=\frac{1}{R_He})$	
(3 the charge carrier mobelity (h = - RH)	
(3) the mean drift velocity of charge carrier ($v_d = \frac{V_H}{8W}$)	
-	6 Measurement of magnetic fields.	
	the same of the same and the same of the s	
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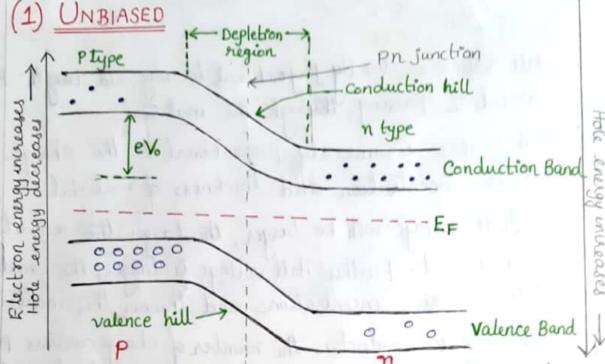


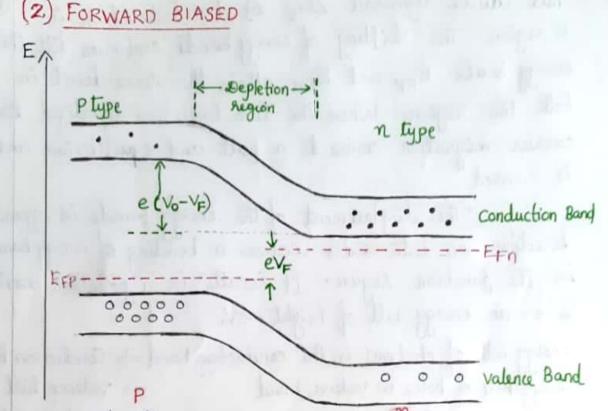
Figure shows the energy level diagram of an unbiased diode. Initially at the instant of formation of Pn junction, the fermilevel on pside and n side are at different positions. In order to establish equilibrium the fermilevel in both regions must come to same level Hence the energy bands get displaced in opposite direction.

The occupancy of energy level by electrons in conduction band on notice is high and posde is how similarly eoccupancy of energy level by holes in valence band on Posde is high and notice is low. Hence in the conduction band electrons on the 'n'side move into 'p' side similarly in the case of valence band holes on the 'P' side move into 'n' side. As high energy electrons leave n region, the fermi level EFn which represents the average energy of electrons moves downwards. This causes downward shift of band structure in no region. On the posde, holes having high energy leave the valence band in that region. The direction of decrease in hole energy is upward and hence fermi leve EFP moves upward.

The displacement of the energy bands in opposite direction on both sides causes a bending of energy bands in the junction region. It results in a potential barrier Vo or an energy hill of height eVo.

Energy hill of electrons in the conduction band \Rightarrow Conduction hill Energy hill of holes in valence band \Rightarrow Valence hill I't means that the electrons on the n side cannot go into the p region unless they have a minimum energy of eVo. Similarly, the holes on the p'side cannot go into n'side unless they have a minimum energy of eVo.

2 2 3 4 1 1 1 1 1 1 1 1 1



In forward biasing, the negative terminal of external voltage source is connected to n region and positive terminal to n region. The negative terminal of voltage source causes an increase in electron energy and an reproard shift of all energy levels on n side. Similarly the positive terminal connected to p side causes an increase in hole energy and a lowering of levels on p side.

As the displacements of the energy levels occur in opposite directions, the fermi levels Efn and Efp get separated by an amount of energy eV_F. Also the height of potential barrier is reduced by an to e(Vo-V_F) from eV_o. Due to reduction of height of potential barrier, the movements of majority carriers is promoted.

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In reverse biased condition, the positive terminal of the bias voltage connected to the n-side reduces the energy of electrons. Therefore energy bands on nside are displaced downwards. Similarly, the negative terminal connected to Pside reduces the energy of holes in Pregion. Hence the energy bands on Pside are displaced upwards. Due to the displacement of these energy bands in opposite direction, the Fermi level get separated by an amount of energy eVR. The barrier height in this case increases to a value of e(Vo+VR). Hence electrons (majority carrier) in n region cannot clemb the conduction hill to go to pregion. Similarly holes in pregion cannot float up the valence hill to go into n region. The diffusion of majority carriers is totally stopped. However the barrier does not influence the drift motion of minorety carriers.

(22)

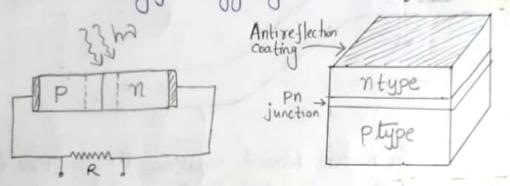
Applications of Semiconductors.

1 Photovoltaic Cell - Solar Cell

Principle: Photo voltaic Effect (i.e Conversion of light energy into electrical energy)

In photovoltaic effect when certain materials being exposed to radiation generates electron-hole pairs available for conduction. As a result a voltage is developed across the material.

Condition: ⇒ The radiation energy E=h v should be greater than the bandgap energy Eg of the material



Solar cell is a p-n junction diode with very high doping level. It consist of a ptype material on which thin layer of n type material is grown. The top layer is thin so that incident solar energy can reach the junction area. When the solar radiation is incident on device (F=h2> Eg) electron—hole pairs are generated in both p and n region. The majority of them cannot recombine in the regions. They reach the depletion region at the junction where an electric field due to space charge separates them. Electron in the p region are drawn into n region and holes in the n region are drawn into p region. It results in accumulation of charge on the two sides of the junction and produces a potential difference called photoemf. If a load is connected across the cell a current flower through it

(2) Light Emitting Diode (LED)

A light emitting diode is a semiconductor diode that gives off light when it is forward brased. LEDs are generally fabricated rusing III-IV group element compound semiconductors such as GiaAs, GiaP, GiaAsP etc. which have a direct band gap.

Principle: When a prijunction is forward biased, the electrons and holes diffuse through the function in opposite derection. In this process they recombine with each other in the depletion region and selease some energy called recombination energy. According to energy band structure, during this recombination, the electron comes back to the valence band with release of some energy equal to the band gap energy Eq. (i.e optical energy is released)

In this case the recombination energy &

emitted as optical energy.

The wavelength of emitted light is given by

 $\lambda = \frac{hc}{Fg} = \frac{1.24}{Fg(eV)} lm$

 $E = h\lambda = \frac{hc}{\lambda} = Eg$ $\therefore \lambda = \frac{hc}{Eg}$

The colour of emitted light depends on type of material used.

Material used	Colow
1. Gra As (Grallium Assertide)	Infrared
2. Gra As P (Gallium Arsenide phosphide)	Red or Yellow
3. Grap (Grallium phosphide)	Red or green.

Symbol of LED

Josephysics Terry

Study Well Best Wishes Dr. Tessy P.J